

**CLEANING POLISH ETCH COMPOSITION AND PROCESS FOR A
SUPERFINISHED SURFACE OF A SUBSTRATE**

Abstract of the Disclosure

A cleaning polish etch composition and process for removing slurry particles which adhere to the surfaces of the substrates (e.g., disk substrates, head wafers, etc.) that are superfinished using a slurry. The cleaning polish etch composition comprises a carrying fluid and etchant for etching the substrate and/or attached slurry particles. The composition is applied to the surface of the substrate while a pad mechanically rubs the surface to etch the substrate under polish conditions thereby maintaining the superfinish surface while removing the superfinish polish slurry debris by etching and dilution. Subsequent cleaning with standard soap solutions removes substantially all contamination from the surface of the substrate. In exemplary embodiments, the cleaning polish etch composition and process produced a glass disk substrate and a Sendust head wafer, each having substantially no surface contamination as seen by atomic force microscope (AFM) after standard soap cleaning steps.